ISI Interconnect Systems Inc.

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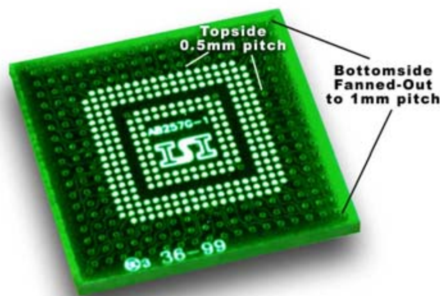
NEWS RELEASE

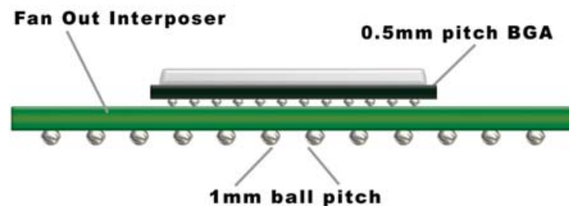
ISI Fan-Out Interposers Reduce PCB Assembly Costs Associated with Micro BGAs

(Camarillo, CA) Fan-out interposers convert fine pitch BGAs to a larger pitch eliminating the additional costs associated with microvias and underfilling on the PCB. They allow the designer to continue using the optimum IC for the design, the fine pitch BGAs, and reduce overall system costs. For example, utilizing a fan-out interposer, a 0.5mm pitch Micro BGA can be converted to a much more usable 1mm pitch, which falls in line with standard design rules providing a more cost-effective solution.

When a fine pitch BGA is driving your design to additional layers, finer line & space, or microvias, a cost analysis will determine if a 'standard' PCB with an interposer is more cost effective than a higher technology PCB without an interposer. The underfill process is much more efficient at the interposer assembly level rather than on a manufacturing line configured for traditional PCB assembly.

For more information visit www.isipkg.com





Interconnect Systems, Inc. 759 Flynn Road Camarillo, California 93012
tel (805) 482-2870 fax (805) 482-8470 www.isipkg.com